



December 2014

# 4N29M, 4N30M, 4N32M, 4N33M, H11B1M, TIL113M 6-Pin DIP General Purpose Photodarlington Optocoupler

Description

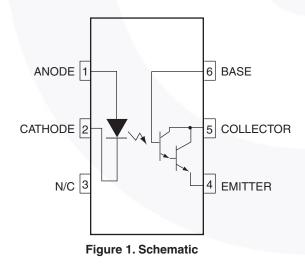
## Features

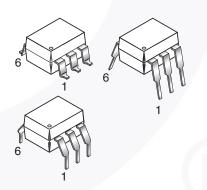
- High Sensitivity to Low Input Drive Current
- Meets or Exceeds All JEDEC Registered Specifications
- Safety and Regulatory Approvals:
  UL1577, 4,170 VAC<sub>RMS</sub> for 1 Minute
- DIN-EN/IEC60747-5-5, 850 V Peak Working Insulation Voltage

## **Applications**

- Low Power Logic Circuits
- Telecommunications Equipment
- Portable Electronics
- Solid State Relays
- Interfacing Coupling Systems of Different Potentials and Impedances

## Schematic





The 4N29M, 4N30M, 4N32M, 4N33M, H11B1M, and

TIL113M have a gallium arsenide infrared emitter opti-

cally coupled to a silicon planar photodarlington.

Figure 2. Package Outlines

## Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter	Characteristics	
Installation Classifications per DIN VDE	< 150 V <sub>RMS</sub>	I–IV
0110/1.89 Table 1, For Rated Mains Voltage	< 300 V <sub>RMS</sub>	I–IV
Climatic Classification		55/100/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
V	Input-to-Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$ , Type and Sample Test with t <sub>m</sub> = 10 s, Partial Discharge < 5 pC	1360	V <sub>peak</sub>
V <sub>PR</sub>	Input-to-Output Test Voltage, Method B, $V_{IORM} \times 1.875 = V_{PR}$ , 100% Production Test with t <sub>m</sub> = 1 s, Partial Discharge < 5 pC	1594	V <sub>peak</sub>
VIORM	Maximum Working Insulation Voltage	850	V <sub>peak</sub>
V <sub>IOTM</sub>	Highest Allowable Over-Voltage	6000	V <sub>peak</sub>
	External Creepage	≥ 7	mm
	External Clearance	≥ 7	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥ 10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.5	mm
Τ <sub>S</sub>	Case Temperature <sup>(1)</sup>	175	°C
I <sub>S,INPUT</sub>	Input Current <sup>(1)</sup>	350	mA
P <sub>S,OUTPUT</sub>	Output Power <sup>(1)</sup>	800	mW
R <sub>IO</sub>	Insulation Resistance at $T_S$ , $V_{IO}$ = 500 V <sup>(1)</sup>	> 10 <sup>9</sup>	Ω

Note:

1. Safety limit values - maximum values allowed in the event of a failure.

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Value	Unit
TOTAL DEVICE			
T <sub>STG</sub>	Storage Temperature	-40 to +125	°C
T <sub>OPR</sub>	Operating Temperature	-40 to +100	°C
ТJ	Junction Temperature	-40 to +125	°C
T <sub>SOL</sub>	Lead Solder Temperature	260 for 10 seconds	°C
P	Total Device Power Dissipation @ $T_A = 25^{\circ}C$	270	mW
PD	Derate Above 25°C	3.3	mW/°C
EMITTER			
I <sub>F</sub>	Continuous Forward Current	80	mA
V <sub>R</sub>	Reverse Voltage	3	V
l <sub>F</sub> (pk)	Forward Current – Peak (300 µs, 2% Duty Cycle)	3.0	А
P	LED Power Dissipation @ T <sub>A</sub> = 25°C	120	mW
PD	Derate above 25°C	2.0	mW/°C
DETECTOR			
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	30	V
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	30	V
BV <sub>ECO</sub>	Emitter-Collector Breakdown Voltage	5	V
P	Detector Power Dissipation @ $T_A = 25^{\circ}C$	150	mW
PD	Derate Above 25°C	2.0	mW/°C
Ι <sub>C</sub>	Continuous Collector Current	150	mA

## **Electrical Characteristics**

 $T_A=25^\circ C$  Unless otherwise specified.

## Individual Component Characteristics

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
EMITTER	EMITTER						
			4NXXM		1.2	1.5	V
V <sub>F</sub> Input Forward Voltage <sup>(2)</sup>	I <sub>F</sub> = 10 mA	H11B1M, TIL113M	0.8	1.2	1.5	V	
		V <sub>R</sub> = 3.0 V	4NXXM		0.001	100	μA
I <sub>R</sub> Reverse Leakage Current <sup>(2)</sup>		V <sub>R</sub> = 6.0 V	H11B1M, TIL113M		0.001	10	μA
С	Capacitance <sup>(2)</sup>	V <sub>F</sub> = 0V, f = 1.0 MHz	All		150		pF
DETECTO	DR						
BV <sub>CEO</sub>	Collector-Emitter Breakdown	I <sub>C</sub> = 1.0 mA, I <sub>B</sub> = 0	4NXXM, TIL113M	30	60		V
	Voltage <sup>(2)</sup>		H11B1M	25	60		V
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage <sup>(2)</sup>	$I_{C} = 100 \ \mu A, \ I_{E} = 0$	All	30	100		V
	Emitten Cellesten Breekdeure		4NXXM	5.0	10		V
BV <sub>ECO</sub> Emitter-Collector Breakdown Voltage <sup>(2)</sup>	$I_{\rm E} = 100 \ \mu A, \ I_{\rm B} = 0$	H11B1M, TIL113M	7	10		v	
I <sub>CEO</sub>	Collector-Emitter Dark Current <sup>(2)</sup>	V <sub>CE</sub> = 10 V, Base Open	All		1	100	nA

#### Notes:

2. Indicates JEDEC registered data.

## Electrical Characteristics (Continued)

 $T_A = 25^{\circ}C$  Unless otherwise specified.

### Transfer Characteristics

Symbol	Parameter	Test Conditions	Device	Min.	Тур.	Max.	Unit
DC CHARA	CTERISTICS						1
		$I_{\rm F} = 10$ mA, $V_{\rm CE} = 10$ V, $I_{\rm B} = 0$	4N32M, 4N33M	50 (500)			mA (%)
I <sub>C(CTR)</sub>	Collector Output Current <sup>(3)(4)(5)</sup>		4N29M, 4N30M	10 (100)			mA (%)
		I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V	H11B1M	5 (500)			mA (%)
		I <sub>F</sub> = 10 mA, V <sub>CE</sub> = 1 V	TIL113M	30 (300)			mA (%)
	Saturation Voltage <sup>(3)(5)</sup>	I <sub>F</sub> = 8 mA, I <sub>C</sub> = 2.0 mA	4NXXM			1.0	V
V <sub>CE(SAT)</sub>			TIL113M			1.25	V
		$I_F = 1 \text{ mA}, I_C = 1 \text{ mA}$	H11B1M			1.0	V
AC CHARA	CTERISTICS			•			
t <sub>on</sub> Turr	Turn on Time	$    I_{F} = 200 \text{ mA}, \  I_{C} = 50 \text{ mA}, \\ V_{CC} = 10 \text{ V}, \  R_{L} = 100 \  \Omega $	4NXXM, TIL113M			5.0	μs
	Turn-on Time	$I_{F} = 10 \text{ mA}, V_{CE} = 10 \text{ V}, \\ R_{L} = 100 \Omega$	H11B1M		25		μs
t <sub>off</sub>	Turn-off Time	$I_F$ = 200 mA, $I_C$ = 50 mA, V <sub>CC</sub> = 10 V, R <sub>L</sub> = 100 Ω	4N32M, 4N33M, TIL113M			100	μs
			4N29M, 4N30M			40	μs
		$I_{\text{F}} = 10 \text{ mA}, \text{ V}_{\text{CE}} = 10 \text{ V}, \\ \text{R}_{\text{L}} = 100 \ \Omega$	H11B1M		18		μs
BW	Bandwidth <sup>(6)(7)</sup>				30		kHz

#### Notes:

3. Indicates JEDEC registered data.

4. The current transfer ratio( $I_C / I_F$ ) is the ratio of the detector collector current to the LED input current.

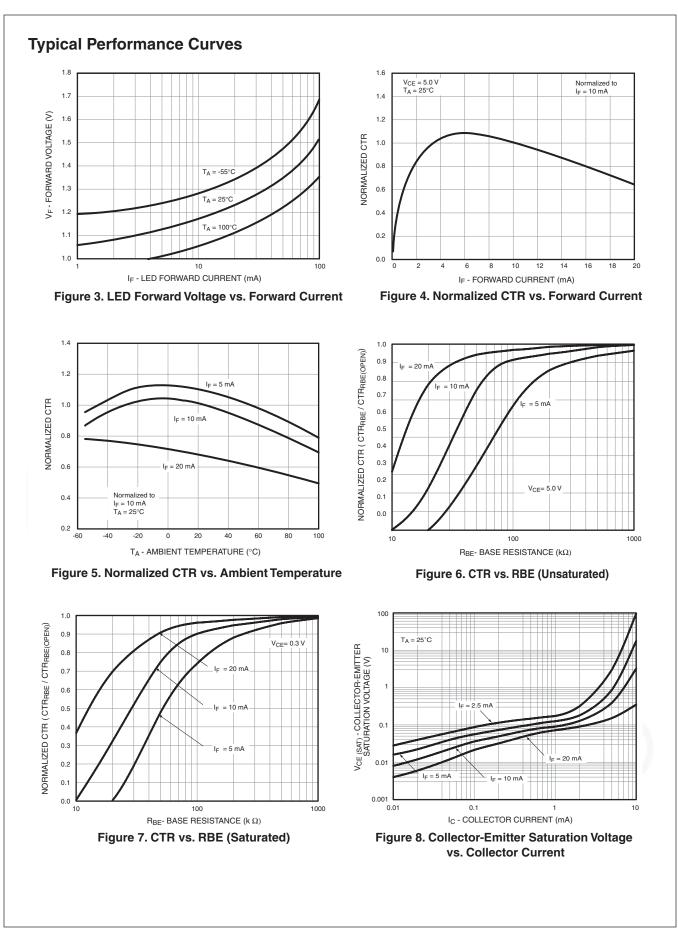
5. Pulse test: pulse width = 300  $\mu$ s, duty cycle  $\leq$  2.0%.

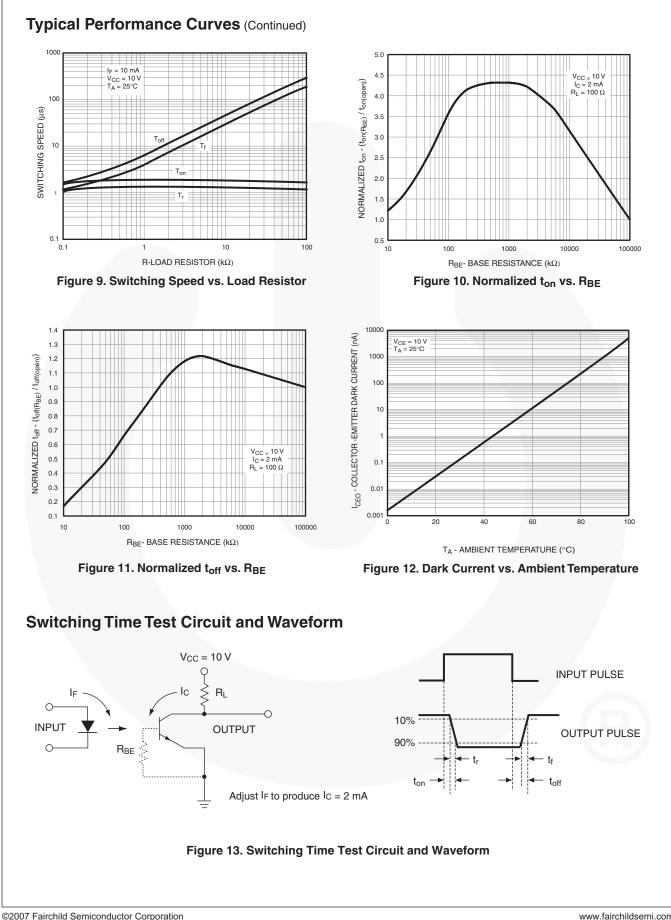
6.  $I_F$  adjusted to  $I_C$  = 2.0 mA and  $I_C$  = 0.7 mA rms.

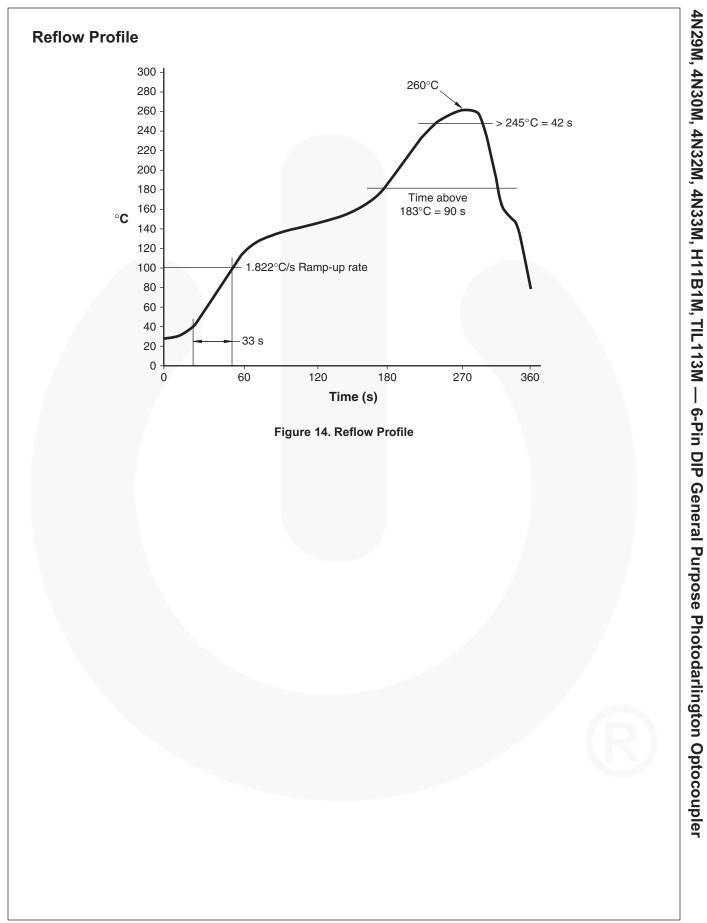
7. The frequency at which  $I_C$  is 3 dB down from the 1 kHz value.

### **Isolation Characteristics**

Symbol	Characteristic	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>ISO</sub>	Input-Output Isolation Voltage	t = 1 Minute	4170			VAC <sub>RMS</sub>
C <sub>ISO</sub>	Isolation Capacitance	V <sub>I-O</sub> = 0 V, f = 1 MHz		0.2		pF
R <sub>ISO</sub>	Isolation Resistance	V <sub>I-O</sub> = ±500 VDC, T <sub>A</sub> = 25°C	10 <sup>11</sup>			Ω







# **Ordering Information**

Part Number	Package	Packing Method
4N29M	DIP 6-Pin	Tube (50 Units)
4N29SM	SMT 6-Pin (Lead Bend)	Tube (50 Units)
4N29SR2M	SMT 6-Pin (Lead Bend) Tape and Reel (100	
4N29VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option	Tube (50 Units)
4N29SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tube (50 Units)
4N29SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option Tape and Reel (1000 United Stress St	
4N29TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option	Tube (50 Units)

#### Note:

8. The product orderable part number system listed in this table also applies to the 4N30M, 4N32M, 4N33M, H11B1M, and TIL113M devices.

## **Marking Information**

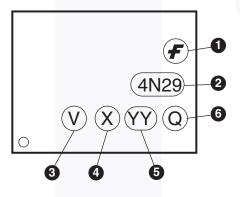
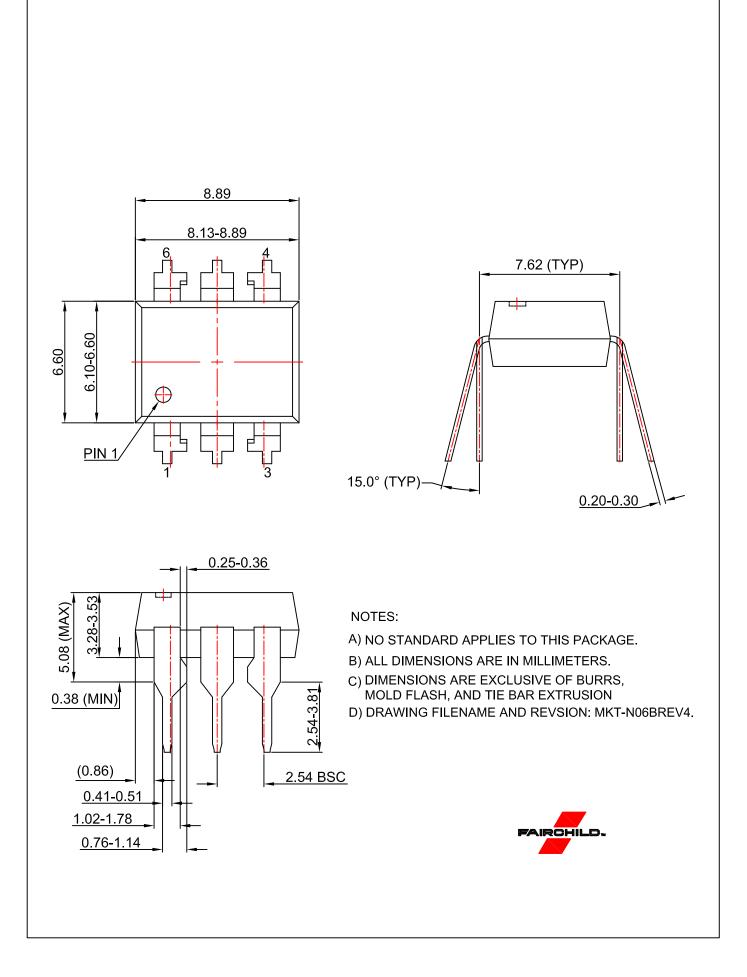
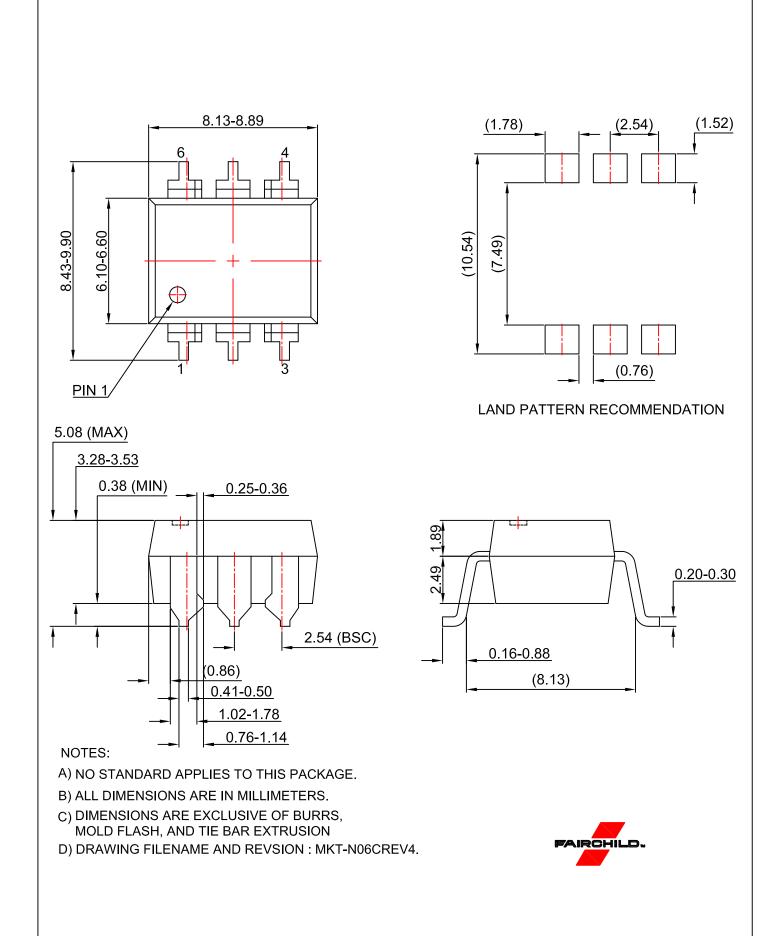


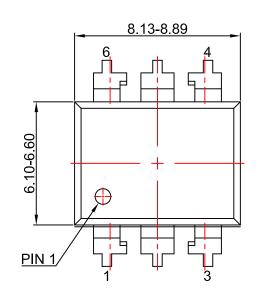
Figure 15. Top Mark

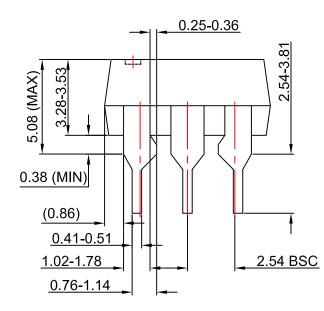
## Table 1. Top Mark Definitions

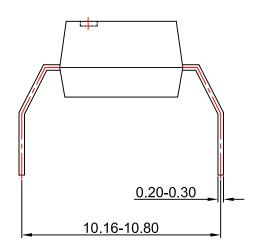
1	Fairchild Logo
2	Device Number
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)
4	One-Digit Year Code, e.g., "4"
5	Digit Work Week, Ranging from "01" to "53"
6	Assembly Package Code











### NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
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